

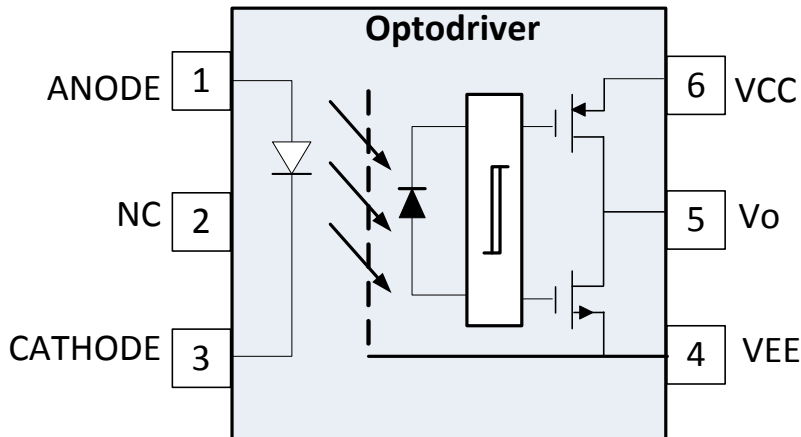
## USING THE Si826X FAMILY OF ISOLATED GATE DRIVERS

### 1. Introduction

Optocoupled gate drivers (a.k.a. “opto-drivers”) provide both galvanic signal isolation and output level shifting in a single package. Opto-drivers are notorious for long propagation times, poor common-mode transient immunity (CMTI), and performance degradation associated with temperature and device age. Modern isolated gate drivers fabricated in CMOS process technology offer higher performance and reliability with none of the downside found in opto-drivers. The Silicon Labs Si826x family of digital isolators (available in peak output currents of 0.6 A or 4.0 A) can directly replace opto-drivers while providing substantial gains in performance and reliability. This application note describes how to correctly apply the Si826x. (For more information about Silicon Labs CMOS isolation technology and comparisons with optocouplers, please see Silicon Labs' white paper “CMOS Digital Isolators Supersede Optocouplers in Industrial Applications”. For more information on the Si826x isolated gate driver family, see the Si826x product data sheet. Both publications are available for download at [www.silabs.com/isolation](http://www.silabs.com/isolation).

### 2. Opto-Driver Overview

The opto-driver shown in Figure 1 consists of an input side LED with a transparent shield to reduce capacitive coupling, an optical receiver, and an output driver. The LED emits light when sufficient current flows from anode to cathode. This light passes through the transparent shield and strikes the optical receiver's photo diode, causing bias current flow from VDD to the gate driver, forcing Vo high. An absence of current through the input side LED causes the gate driver output to transition and remain low.

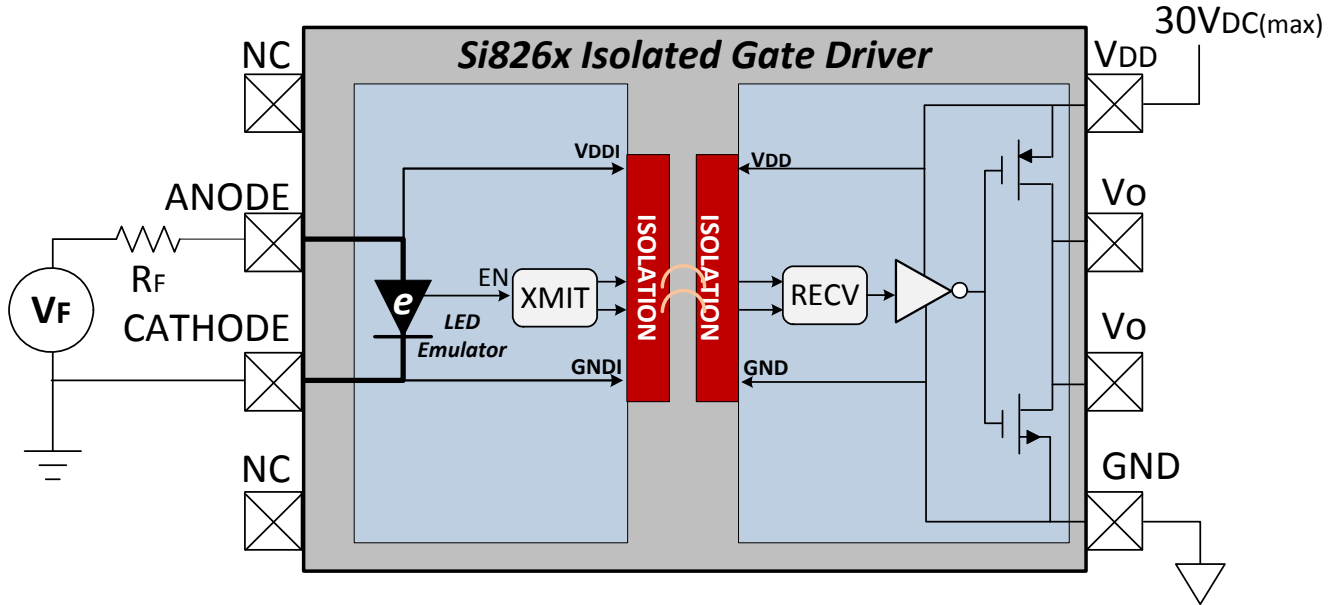


**Figure 1. Opto-Driver Block Diagram**

Opto-driver weaknesses include low reliability, narrow operating temperature ranges, temperature-dependent key timing specifications, and reduced LED device service life and reliability when subjected to excessive temperature, current, and device age. Designers typically allow extra design margin and/or add external components to mitigate these weaknesses.

## 3. Twenty-First Century Isolated Gate Drivers

The input-side diode emulator shown in Figure 2 mimics the behavior of an opto-driver LED to ensure compatibility with existing opto-driver input circuits. The diode emulator enables the high-frequency transmitter when input current  $I_F$  is at or above its threshold value, sending a high-frequency carrier across the isolation barrier to the receiver. This high-selectivity receiver forces the output driver high when sufficient in-band energy is detected. Input current below the  $I_F$  threshold disables the transmitter, causing the receiver to force the output driver low.



**Figure 2. Si826x Isolated Gate Driver**

Si826x benefits include isolated gate drive and level shifting in a single package, strong rejection of external fields, wider operating temperature range, higher precision current thresholds, faster and more consistent timing performance, lower-power operation, and higher reliability compared to opto-drivers. Furthermore, the lack of opto-driver liabilities allows designers to take full advantage of the extra design margin offered by the Si826x. The Si826x achieves this higher level of performance and reliability, primarily due to its architecture and fabrication methodologies:

- **Fabricated in Mainstream Low-Power CMOS**  
 CMOS process technology enables high device integration and speed, low power consumption, high resistance to device temperature and aging effects, stable operation over the  $-40$  to  $+125$  °C temperature range, and exceptionally high reliability. The Si826x isolation barrier lifetime is 10 times higher than that of opto-drivers, and part-to-part matching is 14 times tighter than the Gallium Arsenide (GaAs) process technologies of opto-drivers.
- **High-Frequency Carrier Wave instead of Light**  
 The high-frequency carrier brings the benefits of lower device operating power, faster device response, and superior noise rejection. The fully-differential signal path and high receiver selectivity provide CMTI immunity of  $>50$  kV/ $\mu$ s (typ), external RF field immunity as high as 300 V/m, and magnetic field immunity above 1000 A/m for error-free operation.
- **Use of Proprietary Design Techniques to Suppress EMI**  
 Devices in this family meet FCC Part B emission standards using automotive J1750 (CISPR) test methods. For more information on CMOS isolator emissions, susceptibility, and reliability compared to optocouplers, please see Silicon Labs white paper “CMOS Isolators Supersede Optocouplers in Industrial Applications” available at [www.silabs.com/isolation](http://www.silabs.com/isolation).

## 4. Device Application

### 4.1. Si826x Device Transfer Characteristics

Figure 3 illustrates the device transfer characteristics where an anode current of 6 mA is required to achieve rated CMTI of 35 kV/μs (min) and 50 kV/μs (typ). A driver output-high event begins when the anode current crosses the 6.0 mA current threshold. A driver output-low event begins when the input current falls below the 5.6 mA threshold and continues falling to zero to achieve rated CMTI performance. Note that Si826x devices must have a voltage drop of 1.6 to 2.8 V across the input during those periods when the driver output voltage is high.

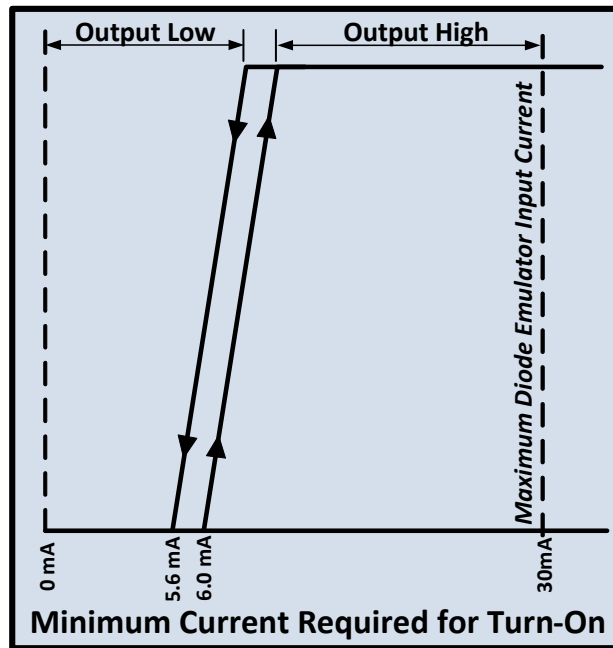
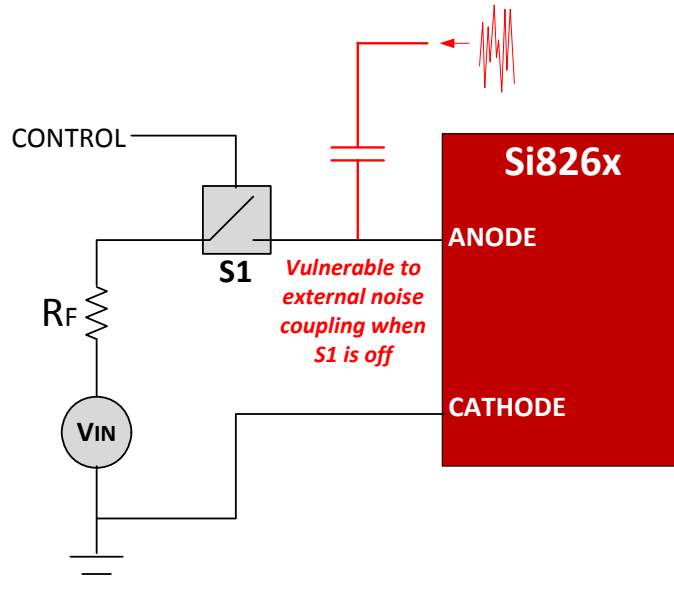


Figure 3. Si826x Device Transfer Characteristics

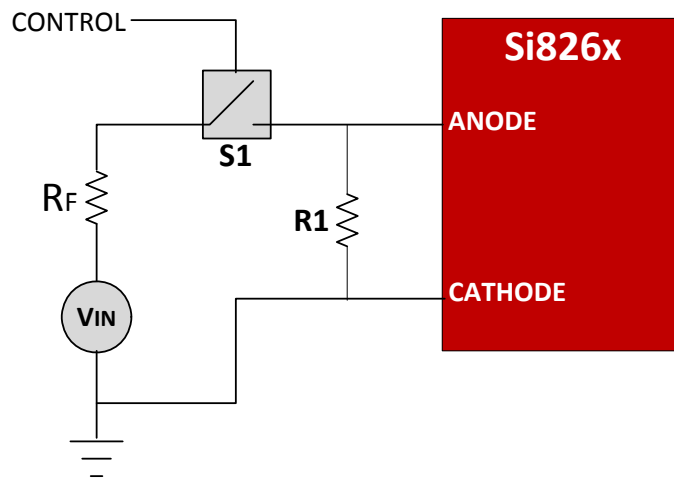
## 4.2. Replacing Legacy Opto-Drivers with the Si826x

The Si826x drops directly into the opto-driver landing site with no changes to the PCB. Opto-drivers sometimes use added external circuitry to enhance noise performance (typical examples include reverse bias and LED shorting switches). These components may be left intact or may be removed depending on the end application. High electrical noise environments should drive the anode input through a low-impedance source for best CMTI performance. The input circuit should not allow the LED emulator to be open-circuited and thereby vulnerable to parasitic coupling that can corrupt data transmission, as shown in Figure 4.



**Figure 4. Poor Input Circuit Design**

The input circuit of Figure 5 shows a simple but effective input circuit using R1 to increase common-mode transient immunity (i.e., the lower the value of R1, the higher the CMTI). Resistor values for R1 can range from 100  $\Omega$  to 1,000  $\Omega$ ; however, these values can be adjusted to meet a designer's needs as long as the device specifications are not violated. The user can optimize the value of R<sub>F</sub> to achieve the best compromise between power dissipation and CMTI performance. Resistor R1 can also be replaced with a switch to further enhance CMTI performance.



**Figure 5. Cost-Effective, High CMTI Circuit**

The circuit shown in Figure 6 uses a complementary buffer (e.g., MCU port I/O pin, dedicated buffer, discrete circuit, etc.) to drive the anode pin. This circuit offers a balance of low impedance off/on drive and relatively low-power operation by optimizing the value of  $R_F$  for best CMTI performance.

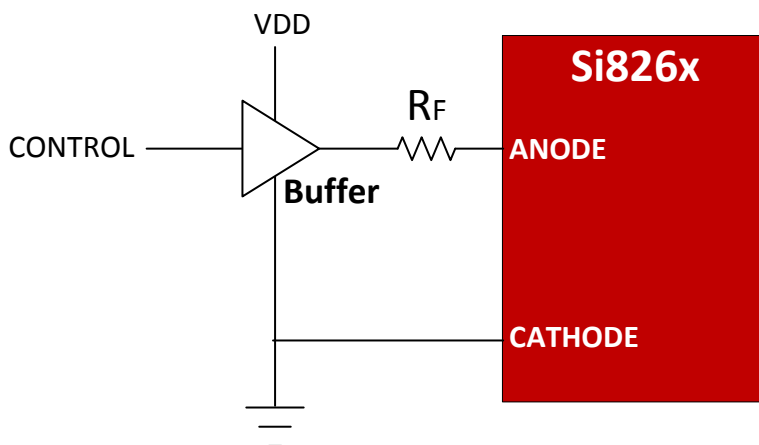


Figure 6. Complementary Output Buffer Drive

## 5. Layout Recommendations

### 5.1. Bypass Capacitors

The output bypass capacitors consist of a parallel combination of a 0.1  $\mu\text{F}$  high-frequency bypass and a 10  $\mu\text{F}$  bulk capacitor connected between VDD and GND and placed as close as possible to the package. Ceramic capacitors should be used for VDD bypass because of their low impedance, high ripple current characteristics, small physical size, and cost-effectiveness.

### 5.2. Layout Guidelines

Ensure that no traces are routed through the creepage/clearance areas of the isolator. It is recommended that the NC pins on the Si826x input side be connected to the input side ground plane since this increases CMTI performance by reducing coupling to the input pins. Minimize the trace lengths between isolators and connecting Si826x circuitry. To enhance the robustness of a design in excessively noisy systems, it is further recommended that the user also include 100  $\Omega$  resistors in series with the inputs/outputs.

## 6. Summary

The Si826x is the ideal upgrade for legacy opto-drivers in both existing and new isolated gate driver designs. These devices outperform their opto-driver counterparts, adding significant gains in device performance and reliability. Si826x family members can directly replace any one of a number of opto-drivers from numerous suppliers.

## DOCUMENT CHANGE LIST

### Revision 0.1 to Revision 0.2

- Updated "2. Opto-Driver Overview" on page 1.
- Updated Figure 2 on page 2.
- Updated "3.2. External Input Circuits" on page 4.
- Updated Figure 4 on page 4.
- Updated "4. Summary" on page 11.

### Revision 0.2 to Revision 0.3

- Updated Figure 3 on page 3.
- Added "3.2.1. Si826x Input Circuit Configurations to Maximize CMT Performance" on page 4.
- Rewrote "3.3. Determining Peak Gate Drive Current" on page 6.
- Rewrote "3.4. Output-Side VDD Bypass Capacitor" on page 7.

### Revision 0.3 to Revision 0.4

- Extensive rewrite of document.

NOTES:

## CONTACT INFORMATION

Silicon Laboratories Inc.  
400 West Cesar Chavez  
Austin, TX 78701  
Tel: 1+(512) 416-8500  
Fax: 1+(512) 416-9669  
Toll Free: 1+(877) 444-3032

Please visit the Silicon Labs Technical Support web page:  
<https://www.silabs.com/support/pages/contacttechnicalsupport.aspx>  
and register to submit a technical support request.

### Patent Notice

Silicon Labs invests in research and development to help our customers differentiate in the market with innovative low-power, small size, analog-intensive mixed-signal solutions. Silicon Labs' extensive patent portfolio is a testament to our unique approach and world-class engineering team.

The information in this document is believed to be accurate in all respects at the time of publication but is subject to change without notice. Silicon Laboratories assumes no responsibility for errors and omissions, and disclaims responsibility for any consequences resulting from the use of information included herein. Additionally, Silicon Laboratories assumes no responsibility for the functioning of undescribed features or parameters. Silicon Laboratories reserves the right to make changes without further notice. Silicon Laboratories makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Silicon Laboratories assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. Silicon Laboratories products are not designed, intended, or authorized for use in applications intended to support or sustain life, or for any other application in which the failure of the Silicon Laboratories product could create a situation where personal injury or death may occur. Should Buyer purchase or use Silicon Laboratories products for any such unintended or unauthorized application, Buyer shall indemnify and hold Silicon Laboratories harmless against all claims and damages.

Silicon Laboratories and Silicon Labs are trademarks of Silicon Laboratories Inc.  
Other products or brandnames mentioned herein are trademarks or registered trademarks of their respective holders.